Title (en)

METHOD FOR SELECTIVE COATING OF A COMPOSITE SURFACE PRODUCTION OF MICROELECTRONIC INTERCONNECTIONS USING SAID METHOD AND INTEGRATED CIRCUITS

Title (de)

VERFAHREN ZUR SELEKTIVEN BESCHICHTUNG FÜR DIE VERBUNDOBERFLÄCHENHERSTELLUNG VON MIKROELEKTRONISCHEN VERBINDUNGSELEMENTEN UNTER VERWENDUNG BESAGTEN VERFAHRENS UND INTEGRIERTER SCHALTKREISE

Title (fr)

PROCEDE DE REVETEMENT SELECTIF D'UNE SURFACE COMPOSITE, FABRICATION D'INTERCONNEXIONS EN MICROELECTRONIQUE UTILISANT CE PROCEDE, ET CIRCUITS INTEGRES

Publication

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Application

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Abstract (en)

[origin: WO2005098087A2] The invention relates to a method for selective coating of specific regions of a composite surface with a conducting film, a method for production of microelectronic interconnections, methods and processes for the production of integrated circuits and, more particularly, the formation of networks of metallic interconnections. The invention further relates to methods and processes for the production of microsystems and connectors.

IPC 8 full level

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CPC (source: EP KR US)

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